

# SOT2119-1

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

27 July 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN68
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-06-2020
<b>Manufacturer package code</b>	98ASA01650D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	68	-	



2 Package outline

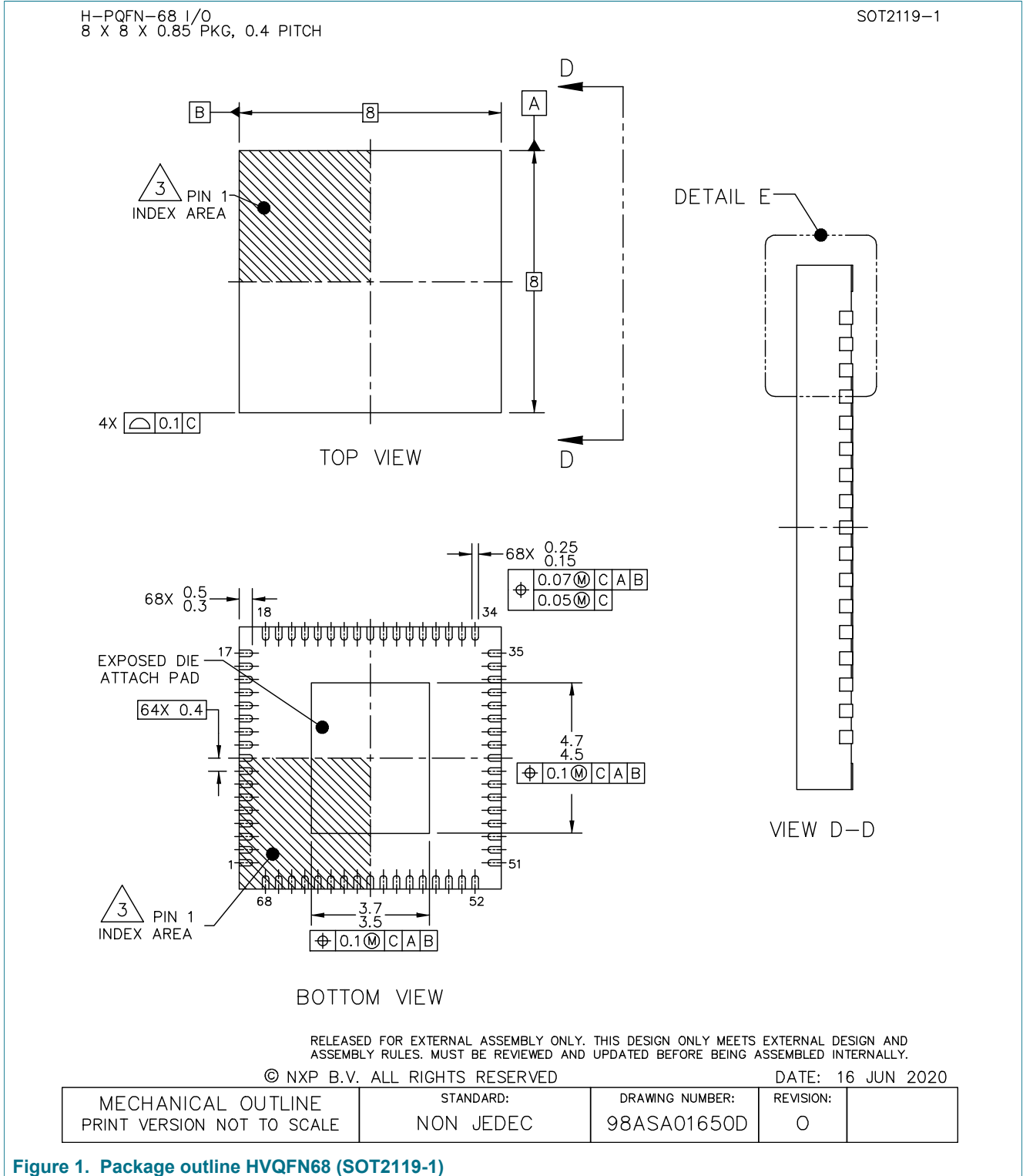


Figure 1. Package outline HVQFN68 (SOT2119-1)



3 Soldering

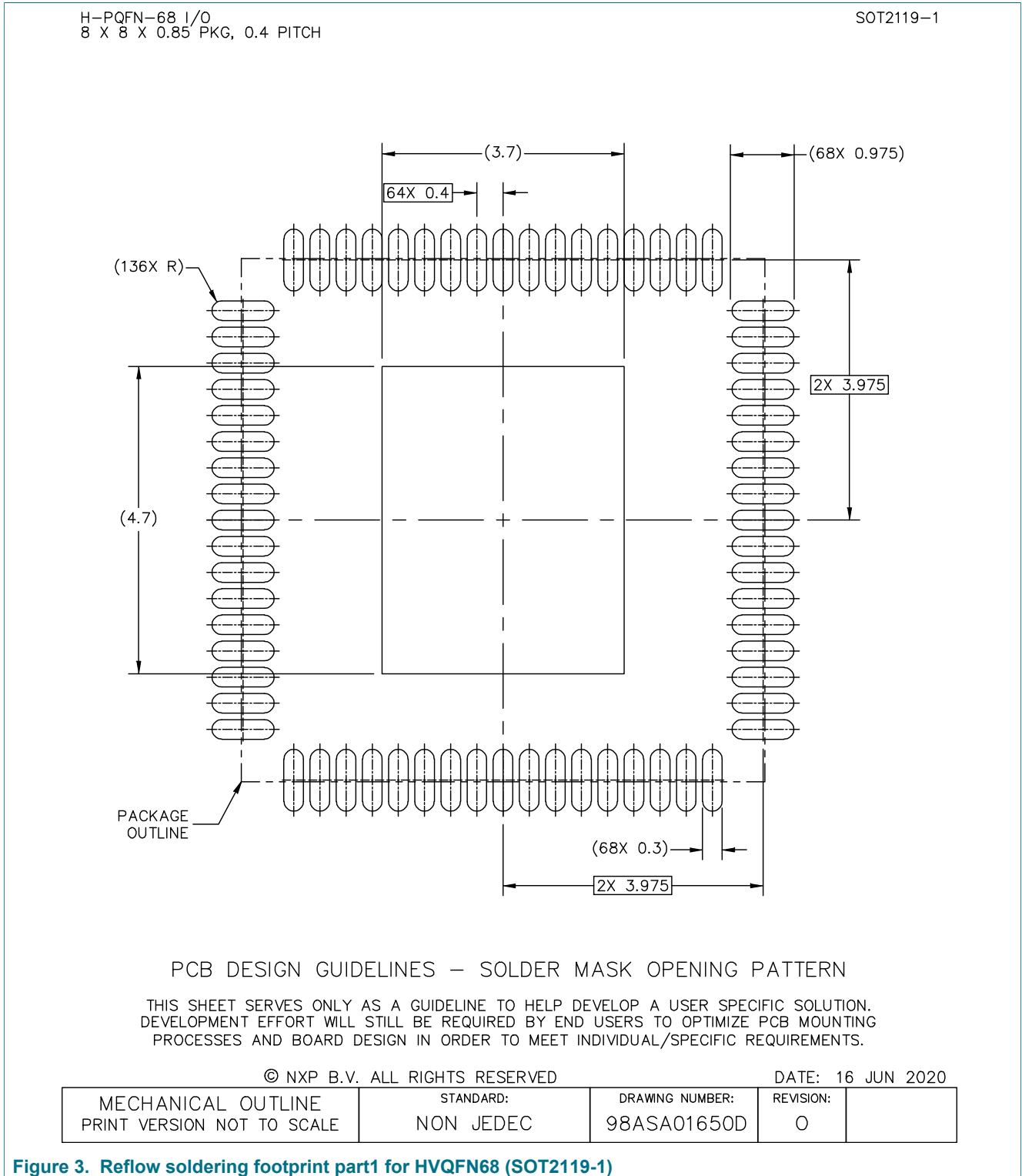


Figure 3. Reflow soldering footprint part1 for HVQFN68 (SOT2119-1)

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

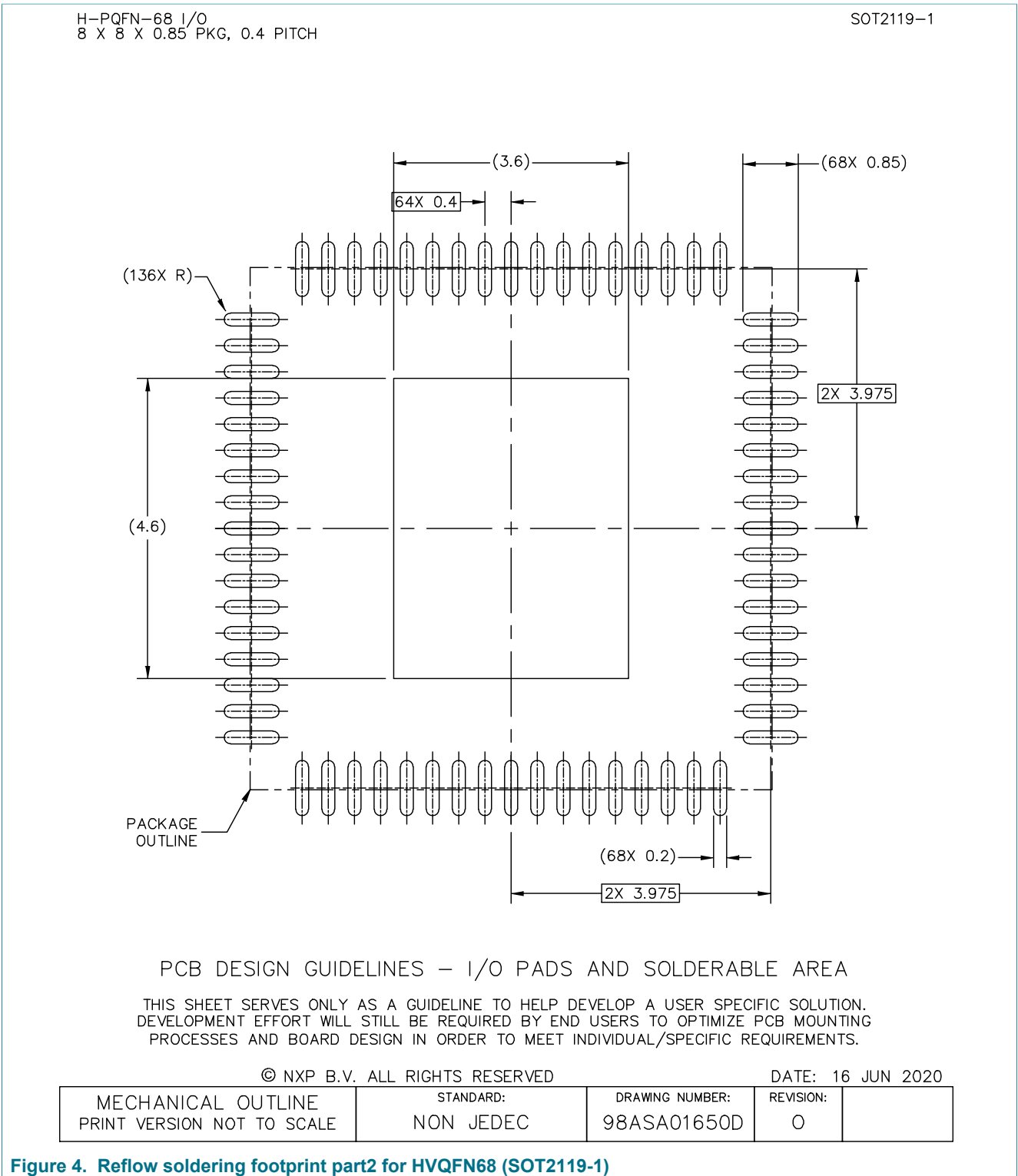


Figure 4. Reflow soldering footprint part2 for HVQFN68 (SOT2119-1)

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

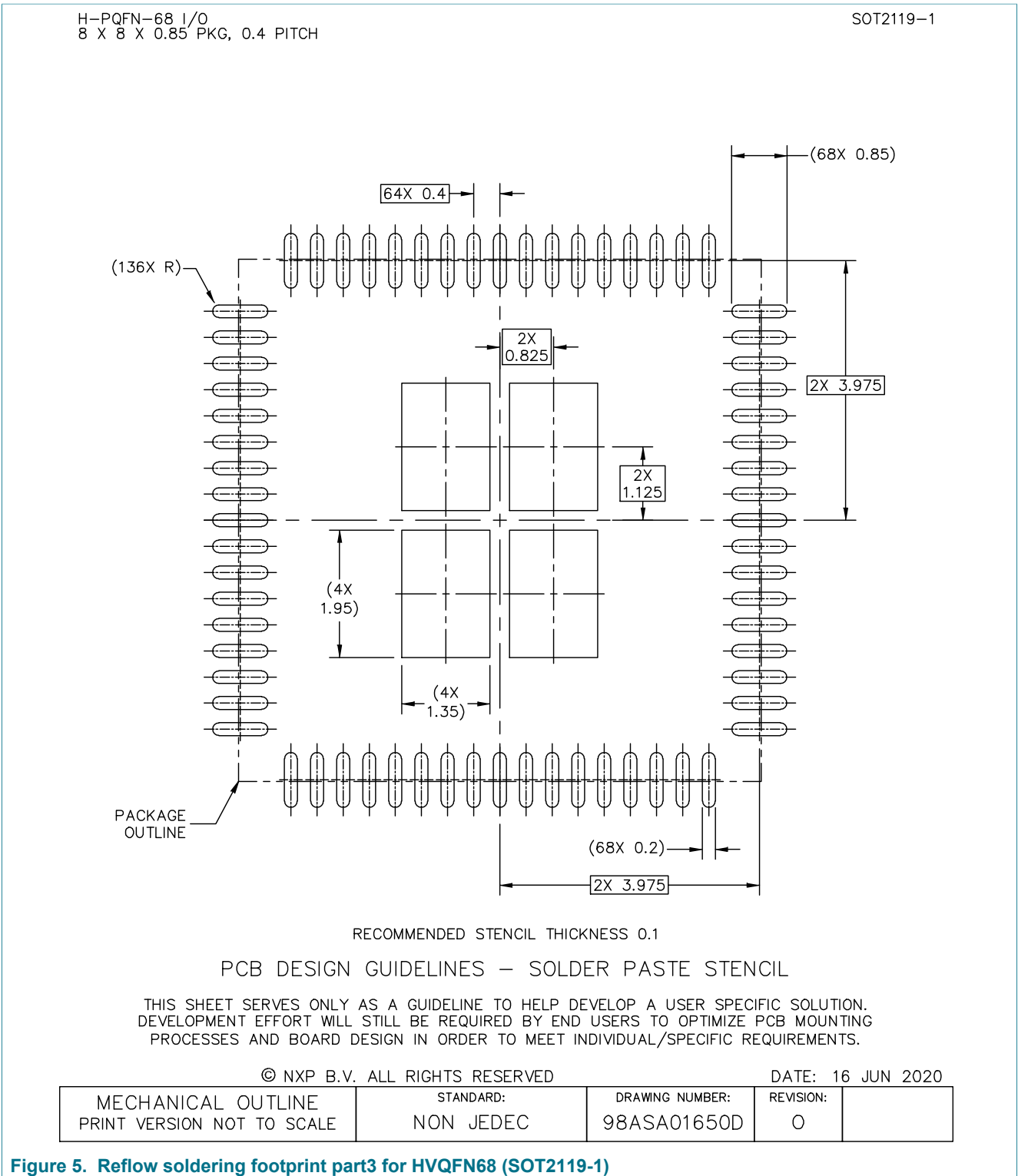


Figure 5. Reflow soldering footprint part3 for HVQFN68 (SOT2119-1)

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

H-PQFN-68 I/O  
8 X 8 X 0.85 PKG, 0.4 PITCH

SOT2119-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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DATE: 16 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01650D	REVISION: 0	
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Figure 6. Package outline note HVQFN68 (SOT2119-1)

## 4 Legal information

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